

**IMAPS Metro Chapter is pleased to offer
the following full day
Professional Development Course**

**April 11, 2013
Holiday Inn Ronkonkoma**

**Introduction to the Basics of Conventional and Advanced
Microelectronic Packaging**

Course Leader: Tom Terlizzi, GM Systems, LLC.

Course Description: The course presents design, manufacturing, materials, quality and reliability information in terms understandable to engineering and non-engineering personnel. Packaging history, characteristics and drivers will be outlined. Types of packages (IC, chip scale, MEMS, Hybrid, MCM, BGA) and substrates (Thick and thin film, co-fired ceramic, organic) and critical differences among them and their applications will be discussed. The course will look at the design selection to meet use and application environments. Step-by-step manufacturing flow for different packages and products will be presented as an example to understand the complexity of processes, materials and equipment involved in their manufacture. Advanced packaging concepts for 2.5D and 3 D will be introduced. Materials selection with respect to application environments will be discussed. Quality and reliability issues related to chip packaging and SMT and their solution will be outlined.

Who Should Attend? It will help the attendees understand the application and assembly of microelectronic package technology on the next level interconnect and the service environment that microelectronic packages must protect its components. Personnel entering the microelectronic packaging field will have a critical look at the quality, reliability and materials issues related to the development and manufacture of chip packages. Non-packaging personnel will learn the ins and outs of chip packaging. Non-technical personnel will learn the material and manufacturing intricacies of microelectronic packages and the associated buzzwords used to describe them.

What you get? Reference notes – paper on thumb drive.

Tom Terlizzi is VP at GM Systems a Management and Technology consulting firm, providing Business & Strategic plans, Acquisitions, Marketing & Sales strategy, Product development for microelectronic projects and business proposal support. He has designed and developed Power management systems, Single board computers, microelectronic circuits, hybrids, COB modules, ICs, RF modules, for over 30 years for military, aerospace, telecom and consumer markets as a VP/GM, Director of marketing, Chief Engineer, Operations/Engineering manager at Aeroflex, Norden/UTC, G.I. Microelectronics and Grumman Aerospace. He spearheaded, acquisitions & mergers of several high tech companies, & ISO9000/Mil-PRF-38534 quality certifications. He received a BEE from CCNY and a MSEE from NYU-Poly & has published several articles, papers and tutorials at international conferences, edited books on electronic packaging, consulted for the DoD on advanced electronic packaging as well as teaching electronics at the US Army Signal School.

Course fees: 500.00 IMAPS Member 600.00 Non Member

Includes Continental Breakfast and Lunch. Also included is admission to the METRO Chapter Vendor Night and

Cocktail Reception immediately following
Group discounts are available

To Register:
Contact Steve Lehnert Phone (650) 644-5218
Email metroimaps@optonline.net
Make Checks Payable to: Metro Imaps
10 Northview Trail
Ridge, NY 11961

Time: 8:00 AM-2:30 PM
Registration and Continental Breakfast start at 7:30 AM
Location: Holiday Inn Ronkonkoma
3845 Veterans Highway
Ronkonkoma, NY 11779
Ph: 631-585-9500

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